

Temperature Compensated Bandpass Filters in LTCC

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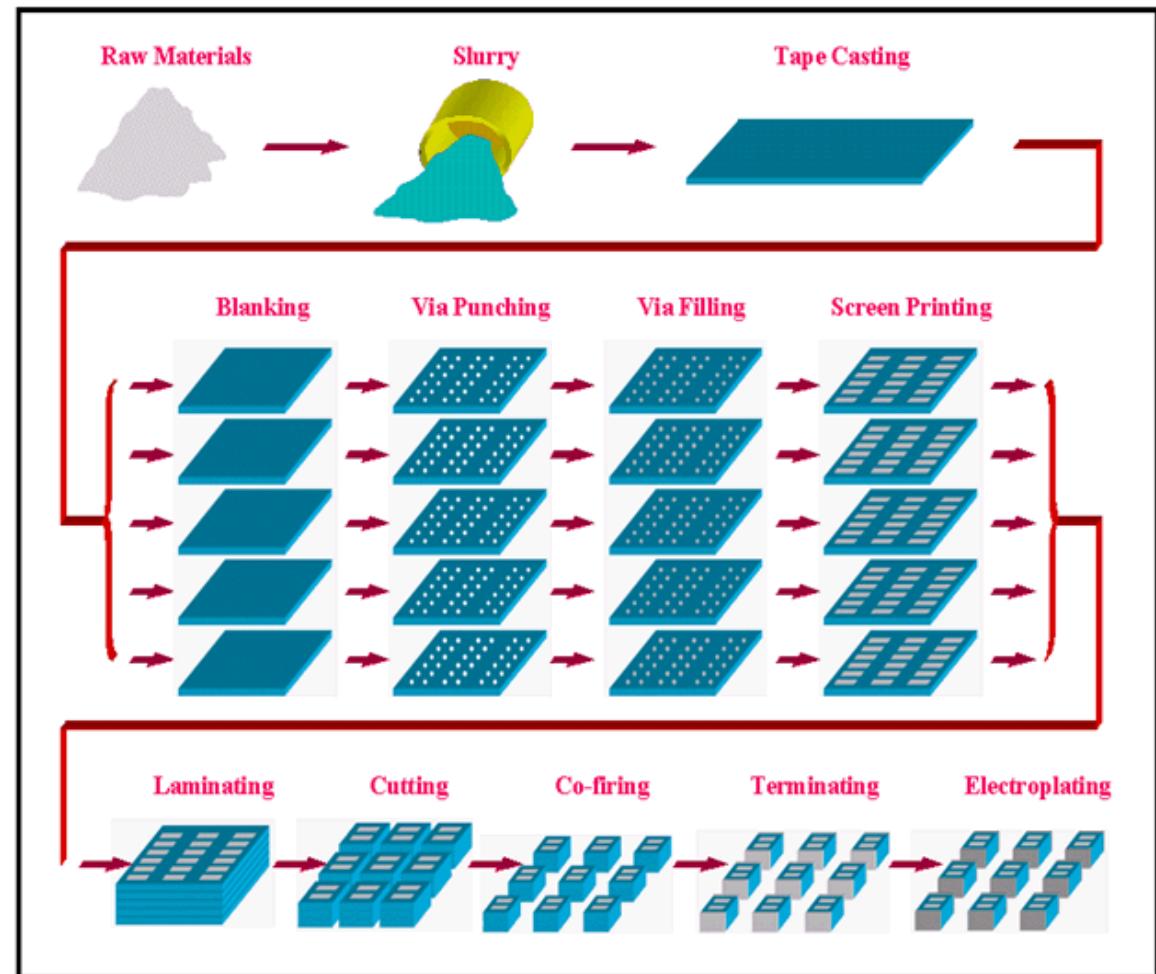


Outline

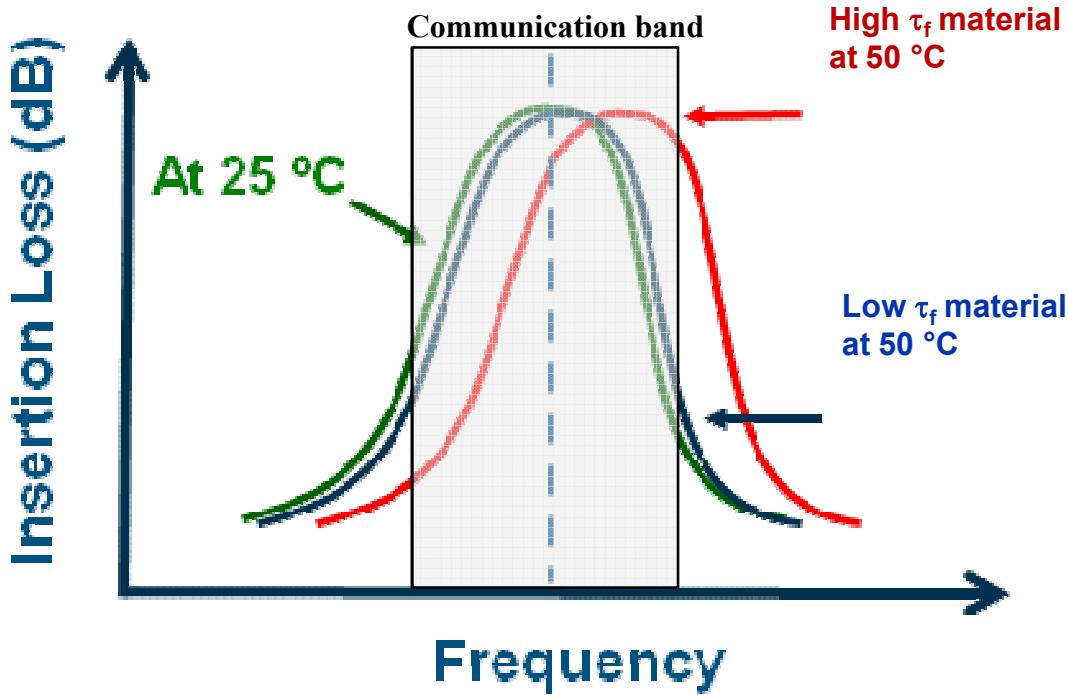
- **Introduction**
 - Low temperature cofired ceramic (LTCC) and RF/MW applications
 - Temperature coefficient of resonant frequency, τ_f
- **Localized temperature stability – adding opposite $0\tau_f$ materials**
 - Development of τ_f compensating materials
 - Simulation and experiment
 - Discussion: Energy filling factor and effective τ_f compensation
- **Temperature stable S-band filters: a demo of localized $0\tau_f$**
- **Summary**

What is LTCC?

- All glass or glass-ceramic tape at sintering temp ≤ 950 °C, typical 850 °C. Ag/Au cofireable
- Multilayer \rightarrow 3D circuitry, passive integration, micro feature formation
- Parallel process \rightarrow high overall yield
- Established manufacture infrastructure



LTCC Dielectric



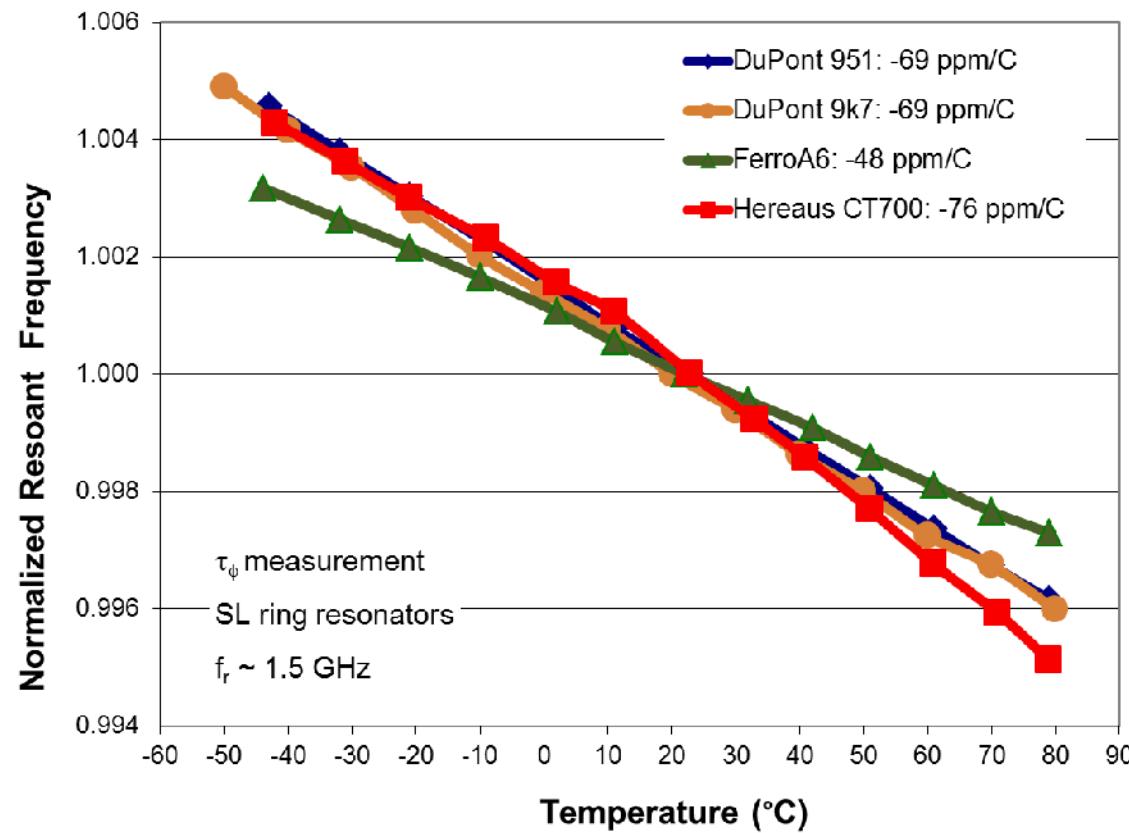
Example:

GSM 900 MHz
 Up-/down-link BW = 25 MHz
 For a $\tau_f = -50 \text{ ppm/}^\circ\text{C}$ materials,
 $\Delta f \sim 6 \text{ MHz}$ over -50 to 80 °C

Shannon-Hartley
 $C = B \log_2(1+S/N)$
 C: channel capacity, B: bandwidth,
 S/N: signal/noise ratio

- Critical dielectric properties for RF/MW applications: ϵ , Q and τ_f
- Low τ_f is needed:
 - For filtering and frequency generation circuits
 - Efficient use of wireless bandwidth
 - To eliminate costly temperature compensation mechanisms

τ_f of Commercial LTCCs



- $\tau_f = -48$ to -80 ppm/ $^\circ$ C
- Designed primarily for packaging, not RF applications

Candidates for τ_f Adjustment

$$\tau_f = -\frac{1}{2}\tau_\varepsilon - \alpha$$

α = coefficient of thermal expansion (CTE)

α : 3-10 ppm/ $^{\circ}$ C $\rightarrow \tau_\varepsilon$ dominates τ_f

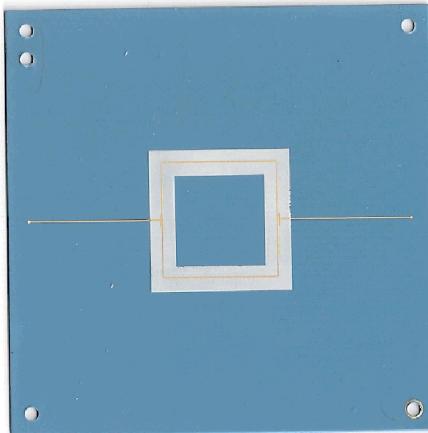
τ_ε is opposite in sign to τ_f

Global 0 τ_f \rightarrow

Localized 0 τ_f \rightarrow

Materials	Density (g/cm ³)	ε	τ_ε (ppm/ $^{\circ}$ C)	τ_f (ppm/ $^{\circ}$ C)	Sintering Temp ($^{\circ}$ C)
TiO ₂	4.23	85	-750	370	~ 1200
CaTiO ₃	3.98	180	-1850	920	~ 1400
SrTiO ₃	5.13	300	-3000	1500	~ 1550
Al ₂ O ₃	4.00	9.6	105	-60	~ 1600
V-glass	2.77	7.3	N/A	N/A	T _g = 625 $^{\circ}$ C

Localized $0\tau_f$ in Existing LTCC?



951 LTCC

- Non-crystallizable glass + Al_2O_3 filler
- $\tau_f = -69 \text{ ppm}/^\circ\text{C}$
- Not designed for RF/MW
- Widely used

Localized $0\tau_f$

- Add-on solution
- Locality = only in needed area/volume

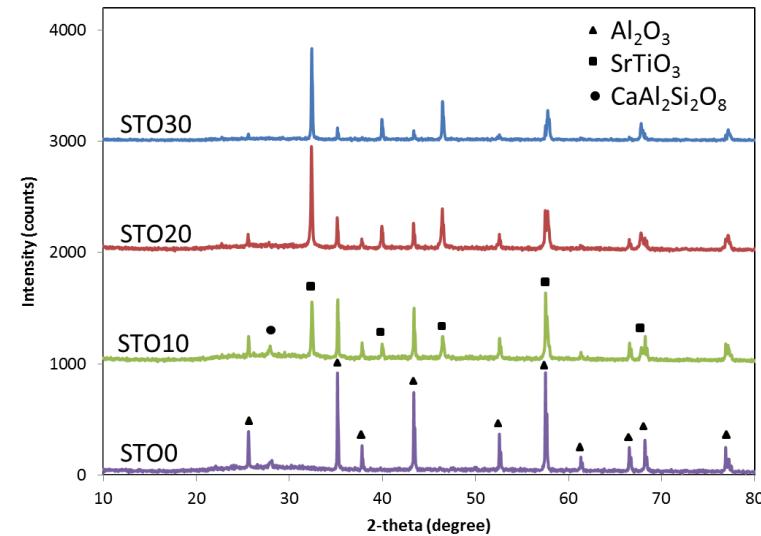
Challenges

- Developing τ_f compensating materials
- Cofiring of τ_f compensating materials in a multilayer LTCC
- Effect of thickness and placement of τ_f compensating material

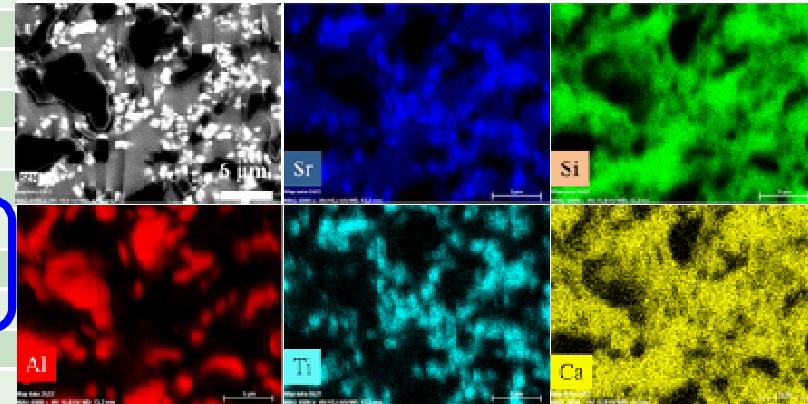
τ_f Adjuster Formulation, Property and Microstructure

Composition	V-glass (wt%)	Al ₂ O ₃ (wt%)	TiO ₂ (wt%)	CaTiO ₃ (wt%)	SrTiO ₃ (wt%)	Total wt%
CMB base	55	45				100
CMB TO15	55	30	15			100
CMB TO30	55	15	30			100
CMB CTO10	55	35		10		100
CMB CTO20	55	25		20		100
CMB STO10	55	35			10	100
CMB STO20	55	25			20	100
CMB STO25	55	20			25	100
CMB STO30	55	15			30	100
CMA STO20	60	20			20	100
CMC STO20	49.5	30.5			20	100
Sample	Archimedes bulk density (g/cc)	ϵ (1 MHz at RT)		τ_ϵ (ppm/ $^{\circ}$ C)	Estimated τ_f (ppm/ $^{\circ}$ C)	
951 LTCC	3.10	7.88		112	-59	
CMB base	3.19	7.79		190	-99	
CMB TO10	N/A					
CMB TO30	2.77					
CMB CTO10	3.20	9.72		83	-45	
CMB CTO20	3.15	12.0		-58	26	
CMB STO10	3.21	9.57		10	-9	
CMB STO20	3.30	12.22		-240	117	
CMB STO25	3.31	13.88		-379	186	
CMB STO30	3.35	15.76		-525	259	
CMA STO20	3.23	11.96		-241	117	
CMC STO20	3.35	12.27		-192	93	

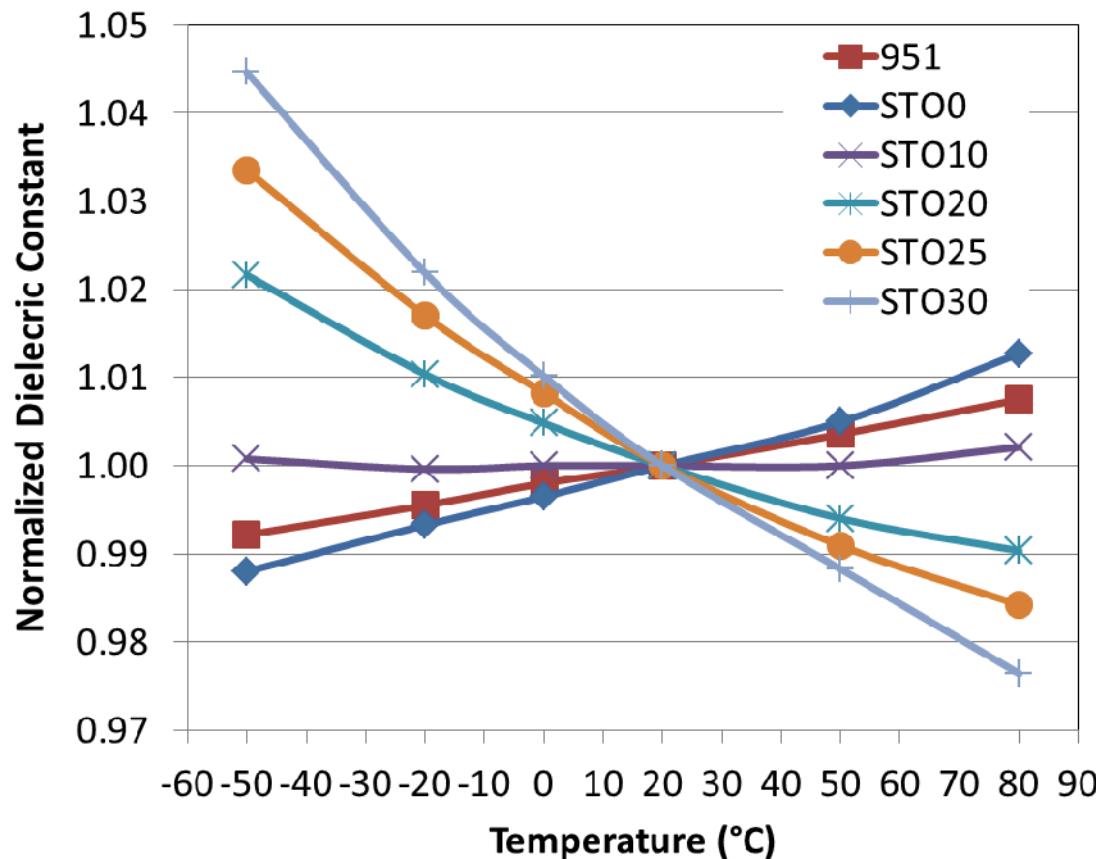
STO XRD: no/minimal reaction



STO20 SEM: no reaction

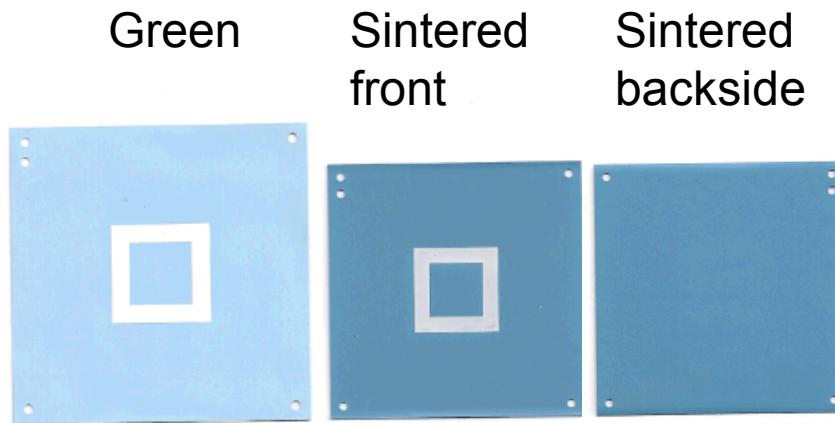


τ_ε of Compensating Materials

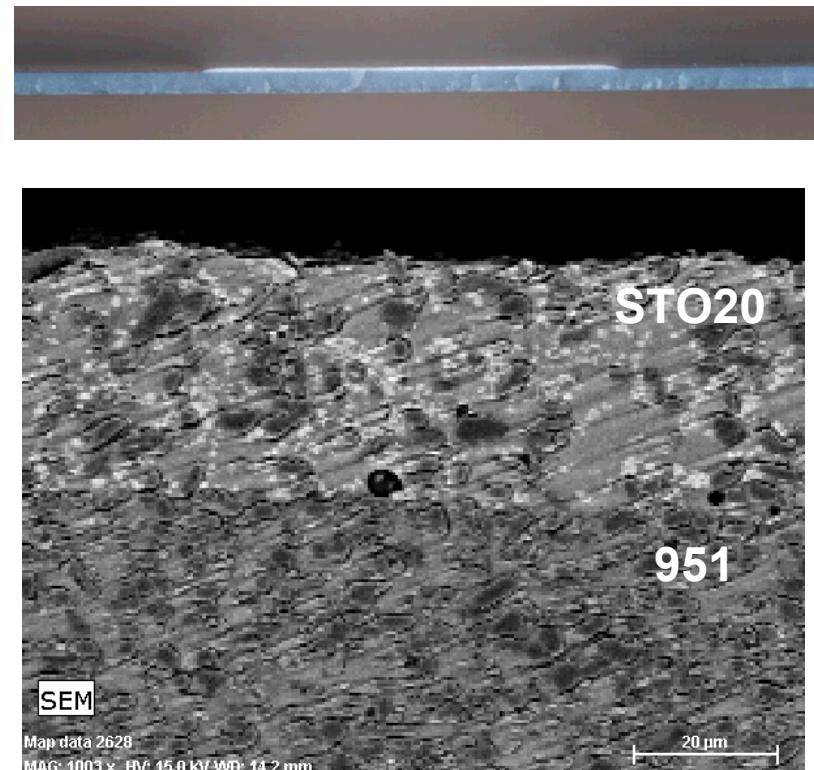


- $\tau_\varepsilon = \text{slope of } f_r \text{ vs } T$, positive \rightarrow negative as STO increases
- STO30 has the largest $\tau_\varepsilon \rightarrow$ positive τ_f

STO20 Cofireability – printed layer on 951



- No deformation of cofired printed STO layer on a 10 mil 951 tape
- Both optical and SEM images show a clean STO20/951 interface, suggesting no or minimal reaction or inter-diffusion

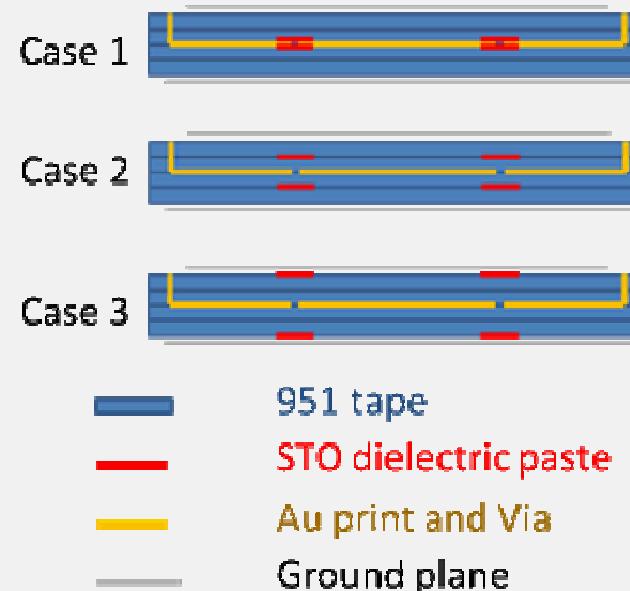


3 Variables

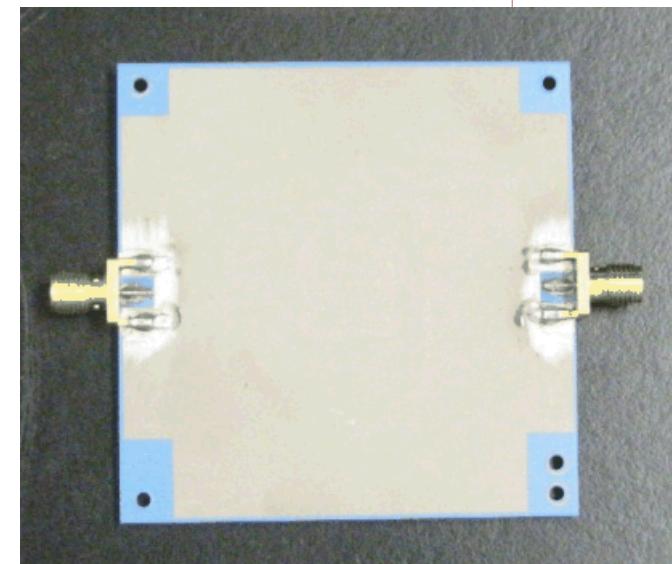
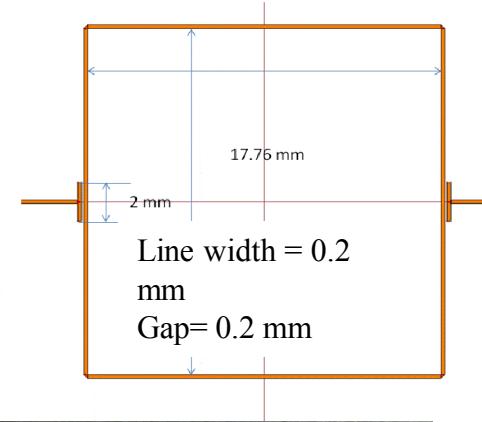
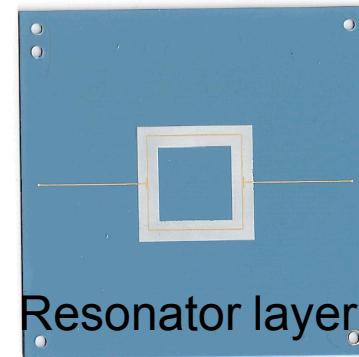
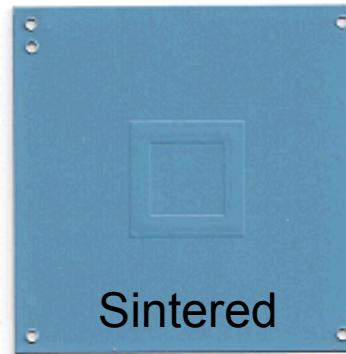
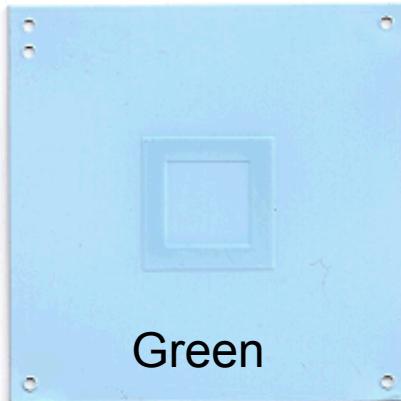
- **STO content:**
 - 20, 25 and 30 wt%

- **STO thickness:**
 - Simulation: 5 to 50 μm
 - Experiment: 20 and 40 μm

- **STO placement**
 - Case 1: next to SL
 - Case 2: one LTCC tape away from SL
 - Case 3: two tape layers away from SL, just under surface ground planes

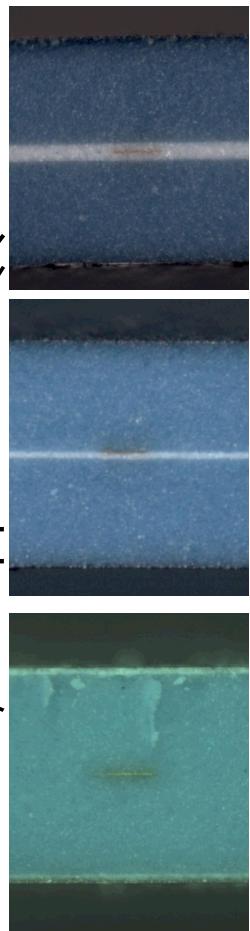
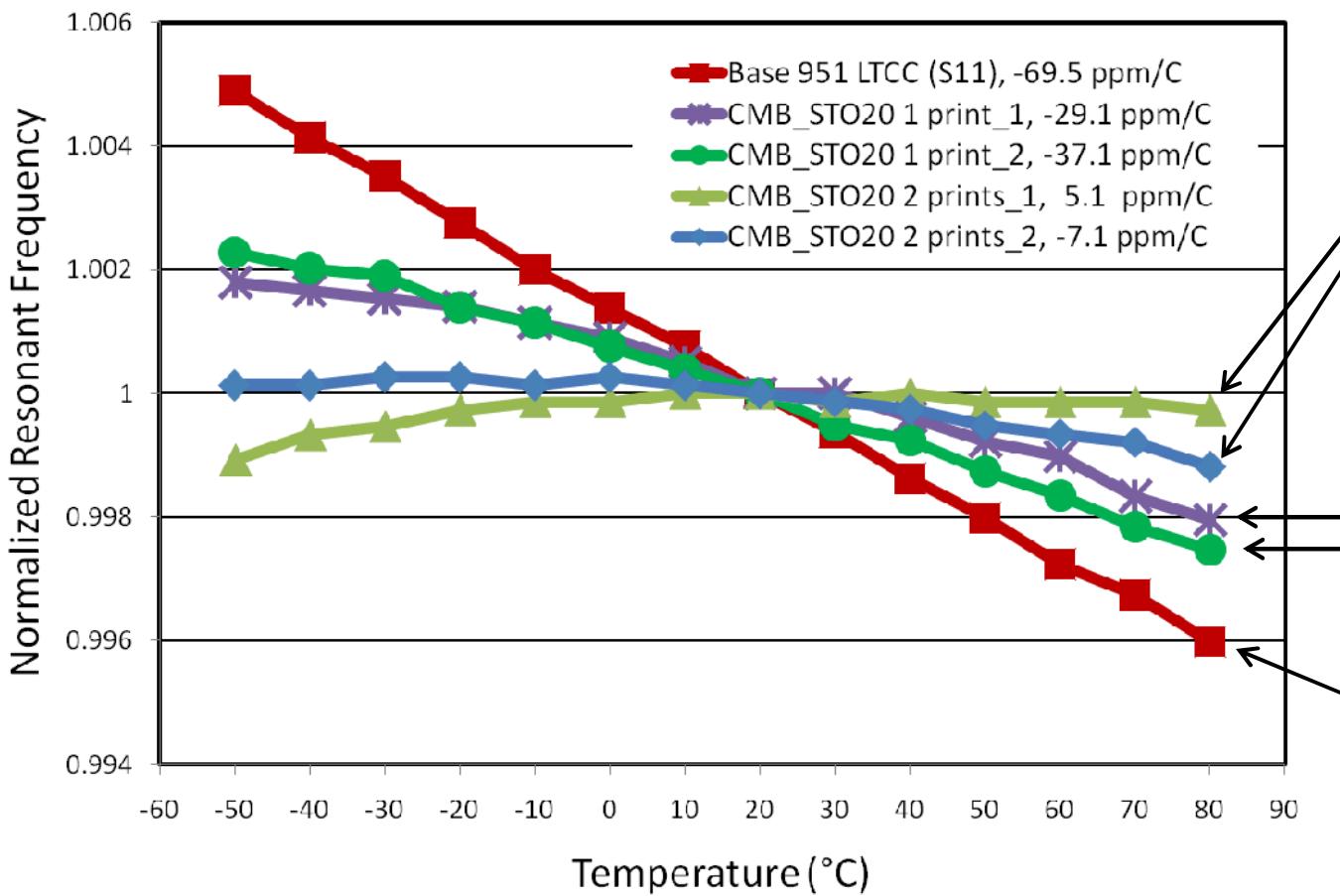


SL Resonator Panels



- Standard LTCC fabricated with 951 matching conductors
- 4 layers of 10 mil 951 tape. 50Ω lines. $f_r = 1.5$ GHz
- No localized deformation, indicating no sintering mismatch
- Embedded STO shown as “embossed” feature on the non-contact side during lamination

τ_f Results



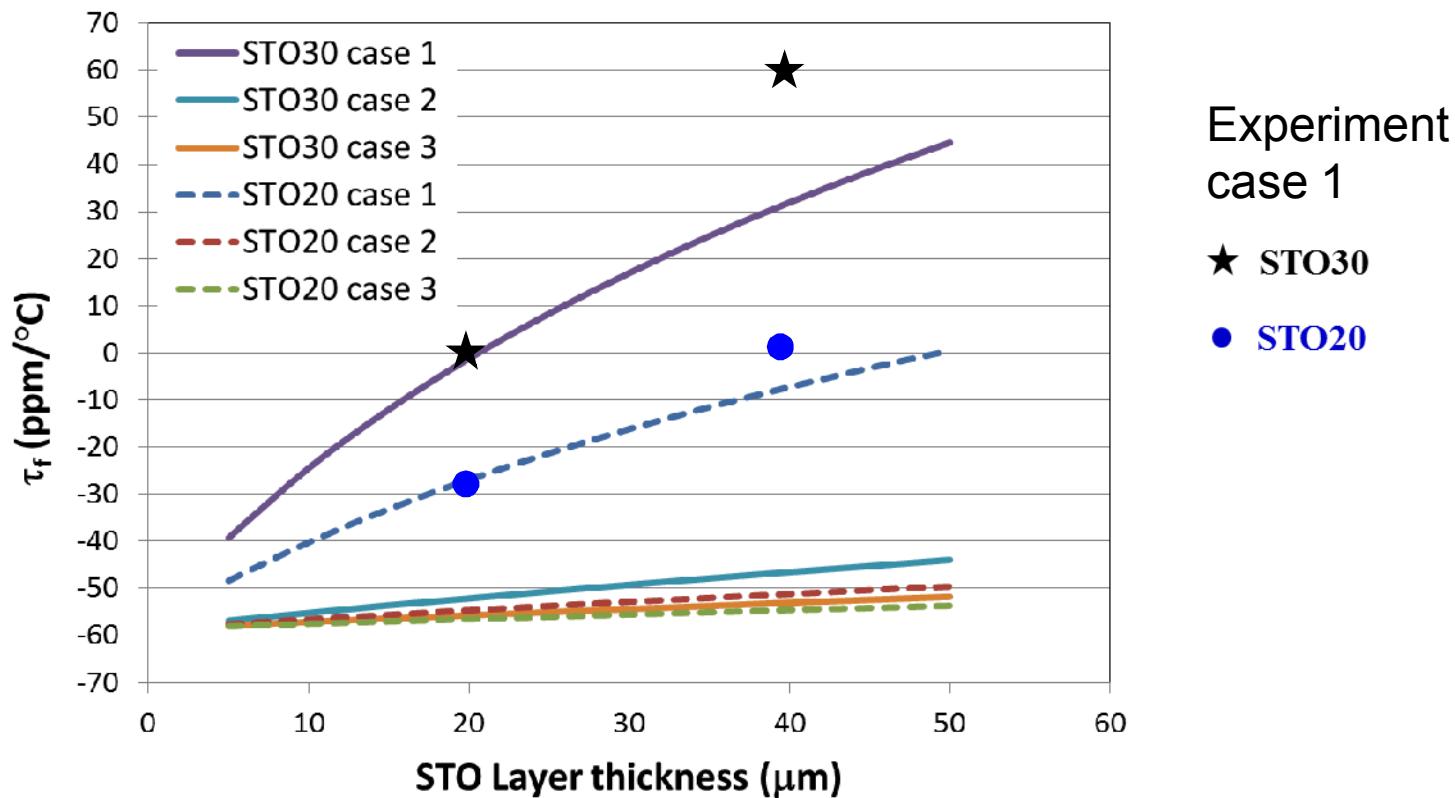
- A true, near zero or zero τ_f is achievable
- Variation of τ_f , possibly by varying the STO20 thickness

SL Resonators

STO composition	Appx STO Thickness (μm)	τ_f (ppm/ $^\circ\text{C}$)		
		Case 1	Case 2	Case 3
STO20	20	-28.8	-67.5	-71.2
	40	<u>1.9</u>		
STO30	20	<u>1.0</u>	-61.7	-69.3
	40	60.0	-54.8	-62.3

- Only in case 1 a $\sim 0 \tau_f$ is realized
 - STO20
 - $\tau_f = -28.8 \text{ ppm}/^\circ\text{C}$ at $20 \mu\text{m}$
 - $\tau_f = +1.9 \text{ ppm}/^\circ\text{C}$ at $40 \mu\text{m}$
 - STO30
 - $0\tau_f = +1.0 \text{ ppm}/^\circ\text{C}$ at $20 \mu\text{m}$
 - τ_f over-corrected at $40 \mu\text{m}$
- In cases 2 and 3, the τ_f is far from $0 \text{ ppm}/^\circ\text{C}$
- Placing τ_f adjuster next to SL is essential for τ_f compensation

Experiment Versus Simulation



- Good match for STOs at 20 μm
- Simulation underestimate at thicker STO

τ_f of a Dielectric Composite

- τ_f expressed as

$$\tau_f = \sum_i P_i \tau_{fi} \quad P_i = E_i / E_{total}$$

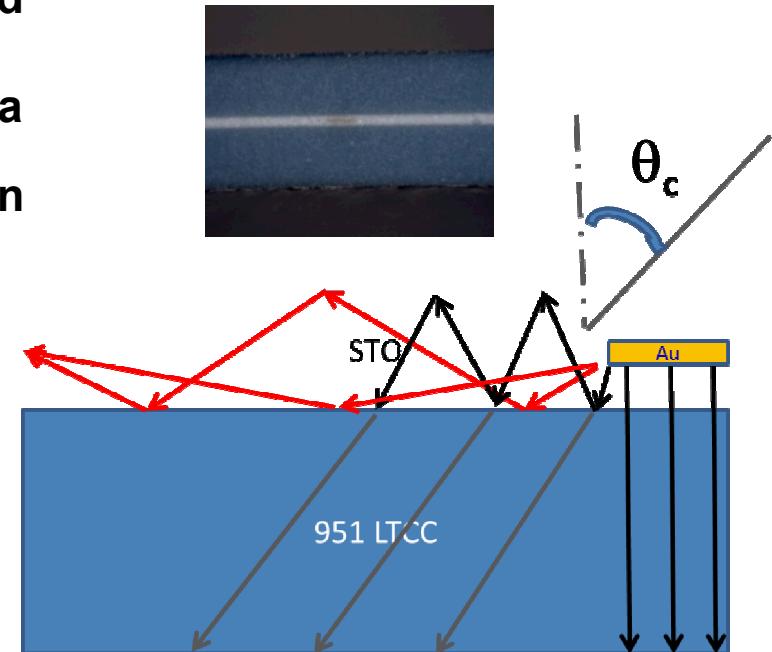
where P_i is defined as the energy filling factor, the fraction of total EM energy confined in dielectric phase i

- P_i depends on dielectric constant, volume, geometry of dielectric i , as well as the EM field distribution inside the dielectric

Energy Concentration in STO Layers Case 1

- Low aspect ratio → fringing electrical field
- EM wave propagates high ϵ → low ϵ media
- Critical angle for total internal reflection in case 1
 - $\epsilon_{STO30} = 15.76$
 - $\epsilon_{LTCC} = 7.88$
- Critical angle (Snell's law)

$$\theta_c = \arcsin\left(\frac{n_{LTCC}}{n_{STO30}}\right) = \arcsin\left(\frac{\sqrt{\epsilon_{LTCC}}}{\sqrt{\epsilon_{STO30}}}\right) = 45^\circ$$



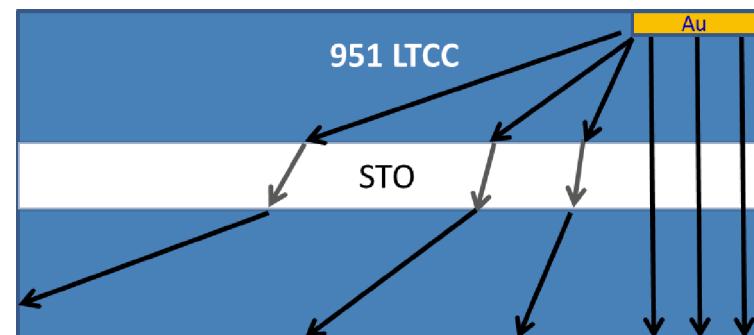
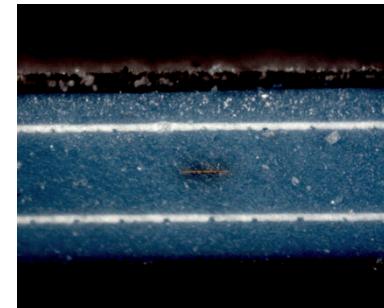
$\theta_c \geq 45^\circ$, total internal reflection in STO

$\theta_c < 45^\circ$, reflection/refraction at the STO-951 interfaces

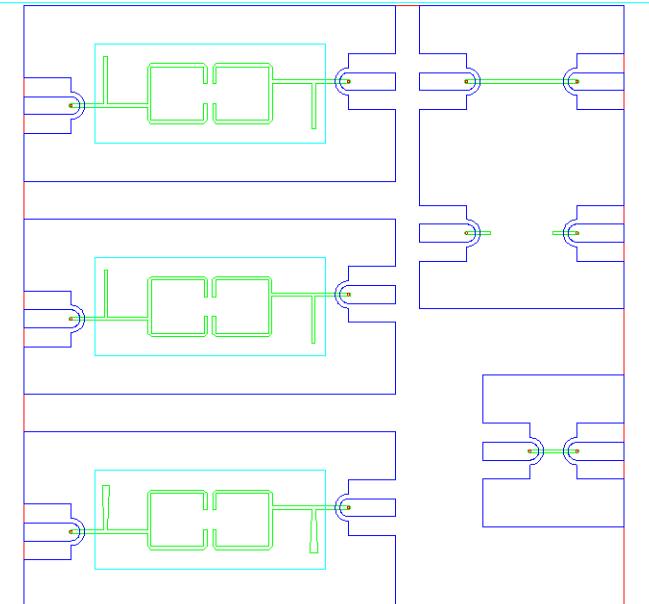
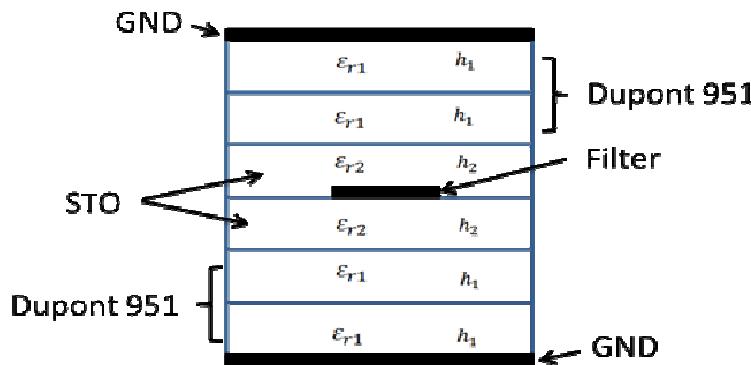
Energy concentration in STO → effective τ_f compensation

No Energy Concentration in Cases 2 and 3

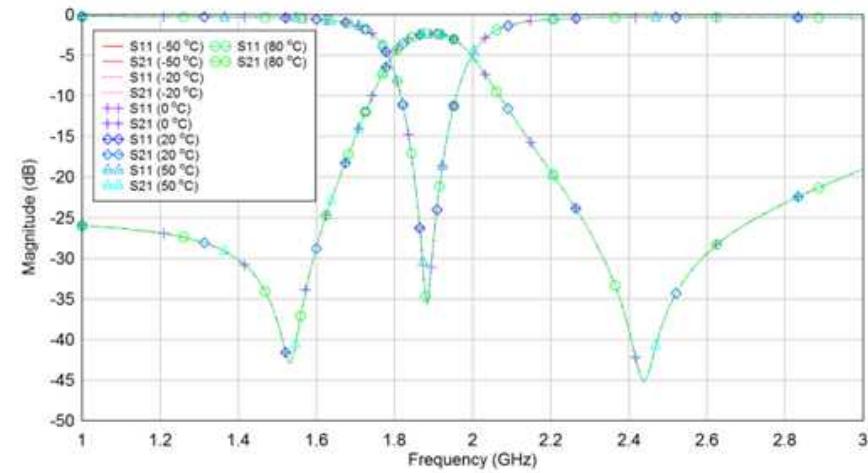
- EM wave propagates low ϵ
→ high ϵ → low ϵ media
- No total internal reflection
- Energy in STO scales to volume
- Overall τ_f of SL resonator is dominated by 951 LTCC



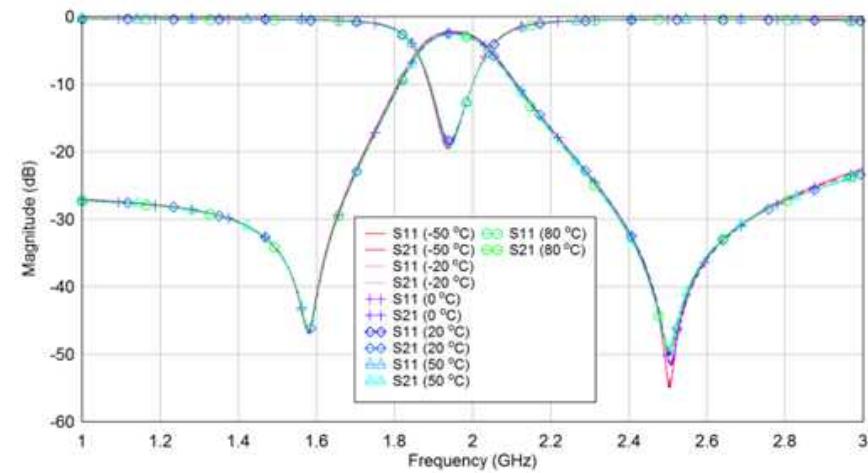
$0\tau_f$ Demo: design of a S-band filter



Simulation ($20\ \mu\text{m}$ STO30)

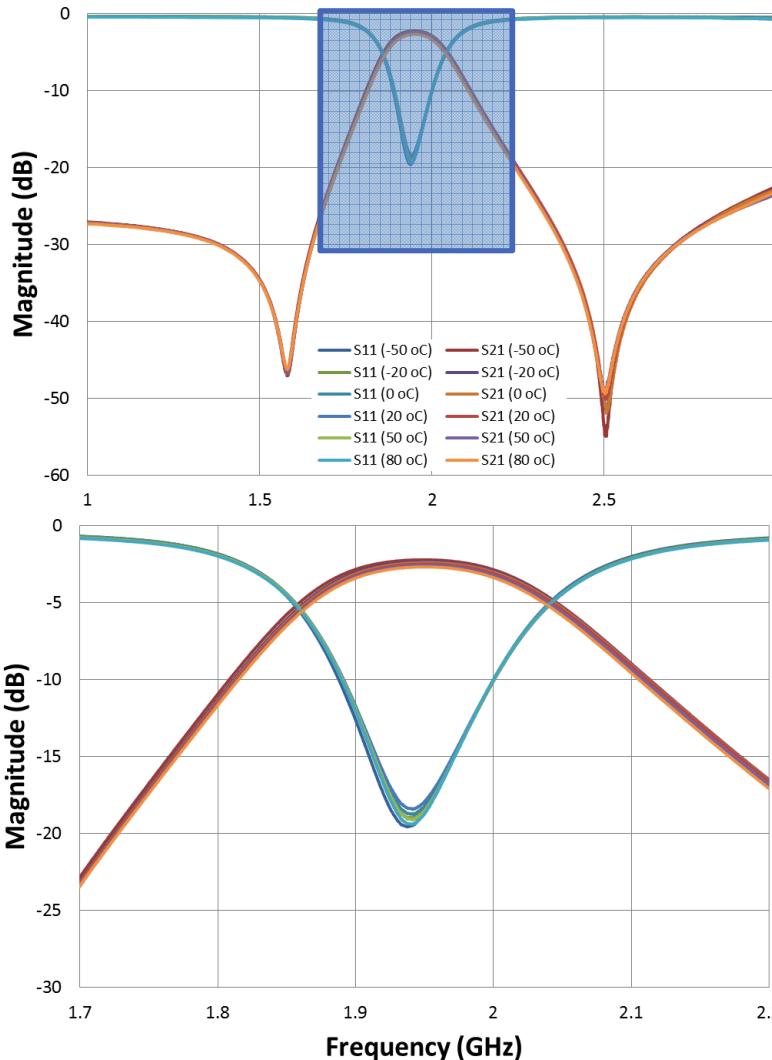


Measurement ($\tau_f = 1.8\ \text{ppm}/^\circ\text{C}$)

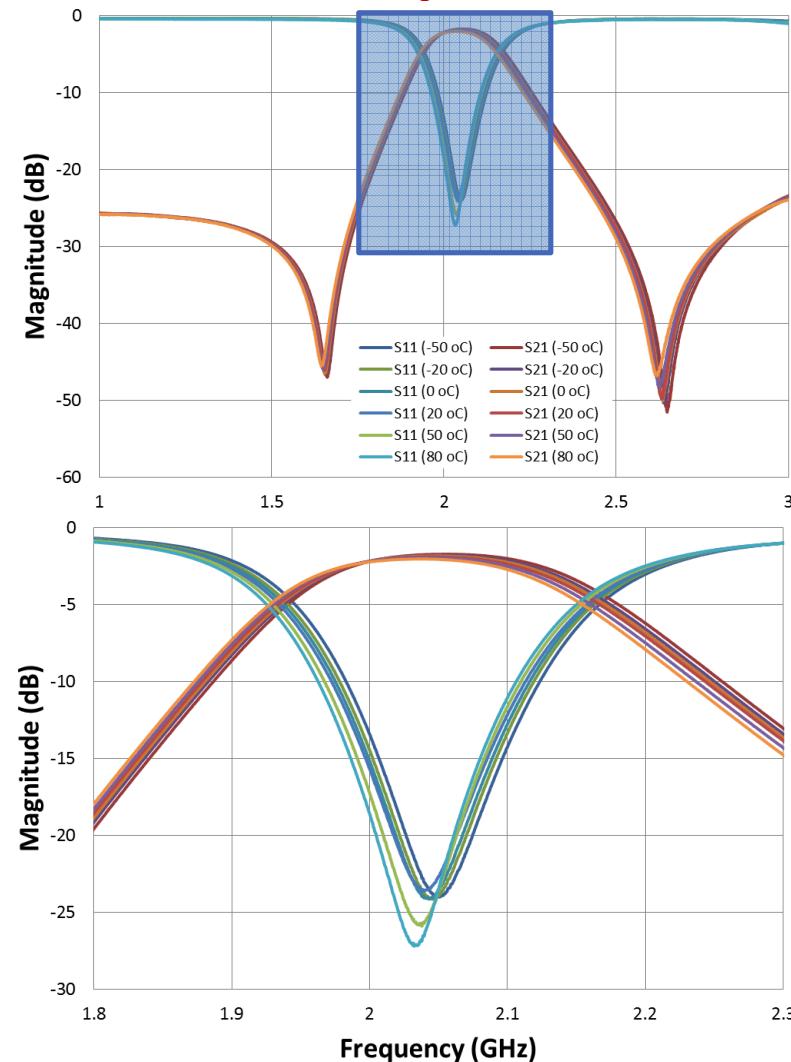


$0\tau_f$ Demo: filter measurement

With $20\ \mu\text{m}$ STO30, $\tau_f = 1.8\ \text{ppm}/^\circ\text{C}$



Without STO, $\tau_f = -71.2\ \text{ppm}/^\circ\text{C}$





Summary

- **SL resonators with a near $0\tau_f$ have been demonstrated by locally integrating a τ_f compensating material in a multilayer LTCC package**
- **Placing STO materials next to the SL is essential for τ_f compensation, due to the EM energy concentration in the STO layers**
- **S-band filter with $0\tau_f$ has been demonstrated**



Acknowledgement

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- This work is supported by the Laboratory Directed Research and Development (LDRD) program at Sandia National Laboratories, a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000

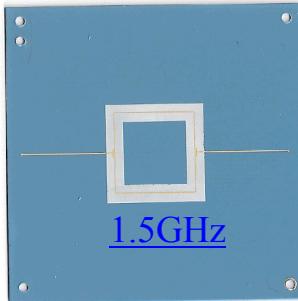


Thank You!



Characterization of τ_f and τ_ε

- Test vehicle; 4 layer LTCC panel



- Test setup



- Test method

- Resonant frequency, f_r , from reflection coefficient, S_{11}
- Temperature range -50 to 80°C

$$\tau_f = \frac{1}{f_r} \frac{\Delta f}{\Delta T}$$

Properties of compensating materials

Composition		Temperature (°C)						τ_ϵ (ppm/°C)
		-50	-20	0	20	50	80	
Dielectric constant	951	7.82	7.84	7.86	7.88	7.91	7.94	118
	Base	7.70	7.74	7.76	7.79	7.83	7.89	190
	STO10	9.58	9.57	9.57	9.57	9.57	9.59	10
	STO20	12.49	12.35	12.28	12.22	12.15	12.10	-240
	STO25	14.34	14.12	13.99	13.88	13.75	13.66	-379
	STO30	16.46	16.10	15.92	15.76	15.57	15.39	-525

- τ_ϵ changes from positive to negative as STO increases
- STO20, STO25 and STO30 are promising for τ_f compensation. STO10 not considered
- Dielectric constant increases as STO increases → lower f_r

ϵ_{eff} of Heterogeneous Multilayer Dielectric

$$\frac{1}{C} = \frac{1}{\pi} \int_0^\infty \frac{[\tilde{f}(\beta)/Q]^2}{\beta} \frac{1}{Y} d\beta$$

$\beta = 2\pi/\lambda_g$: propagation constant, Q: SL charge

$$\epsilon_{\text{eff}} = \frac{C}{C_o}$$

$$\frac{\tilde{f}(\beta)}{Q} = \frac{8}{5} \frac{\sin(\beta w/2)}{\beta w/2} + \frac{12}{5(\beta w/2)^2} \left[\cos(\beta w/2) - \frac{2\sin(\beta w/2)}{\beta w/2} + \left(\frac{\sin(\beta w/4)}{\beta w/4} \right)^2 \right]$$

Fourier transform of the charge density distribution

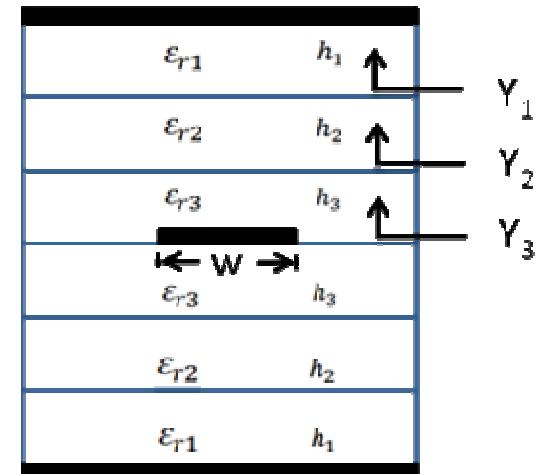
$$Y_1 = \epsilon_o \epsilon_{r1} \coth(\beta h_1)$$

$$Y_2 = \epsilon_o \epsilon_{r2} \frac{Y_1 + \epsilon_o \epsilon_{r2} \tanh(\beta h_2)}{\epsilon_o \epsilon_{r2} + Y_1 \tanh(\beta h_2)}$$

$$Y_3 = \epsilon_o \epsilon_{r3} \frac{Y_2 + \epsilon_o \epsilon_{r3} \tanh(\beta h_3)}{\epsilon_o \epsilon_{r3} + Y_2 \tanh(\beta h_3)}$$

Y_1, Y_2, Y_3 are transverse transmission line admittance

$$Y = 2\epsilon_o \epsilon_{r3} \frac{Y_2 + \epsilon_o \epsilon_{r3} \tanh(\beta h_3)}{\epsilon_o \epsilon_{r3} + Y_2 \tanh(\beta h_3)}$$



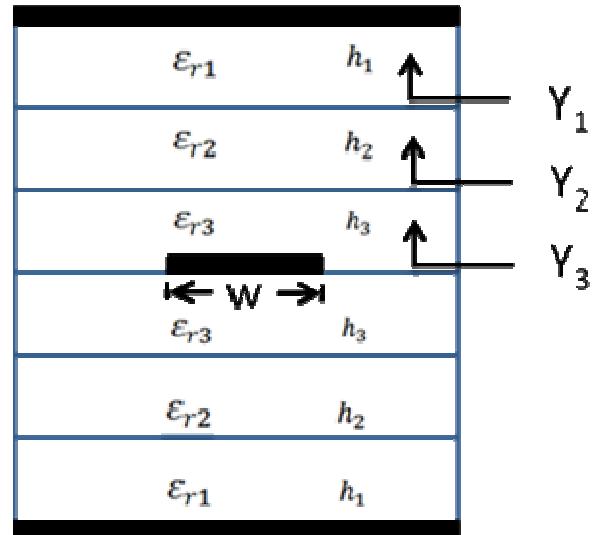
ε_{eff} and f_r

$$\frac{1}{C_o} = \frac{1}{\pi} \int_0^{\infty} \frac{\left[\tilde{f}(\beta) \right]^2}{\beta} \frac{1}{Y_o} d\beta$$

$$\varepsilon_{\text{eff}} = \frac{C}{C_o}$$

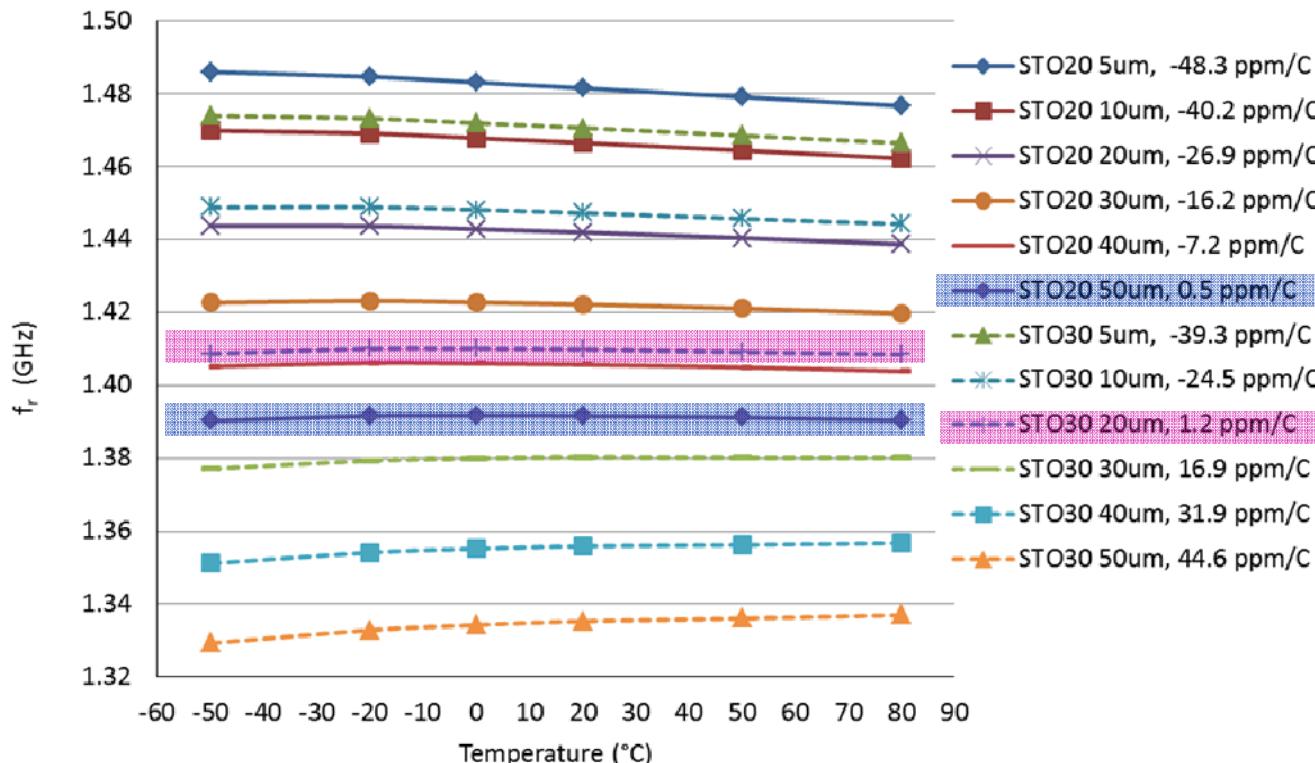
$$Y_{30} = \varepsilon_o \coth[\beta(h_1 + h_2 + h_3)]$$

$$Y_o = 2Y_{30} = 2\varepsilon_o \coth[\beta(h_1 + h_2 + h_3)]$$



Method of Momentum EM simulation $\rightarrow f_r$

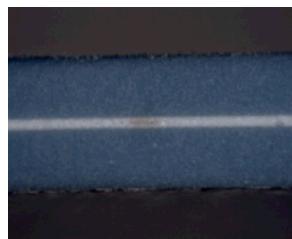
Effect of Composition and Thickness for Case 1



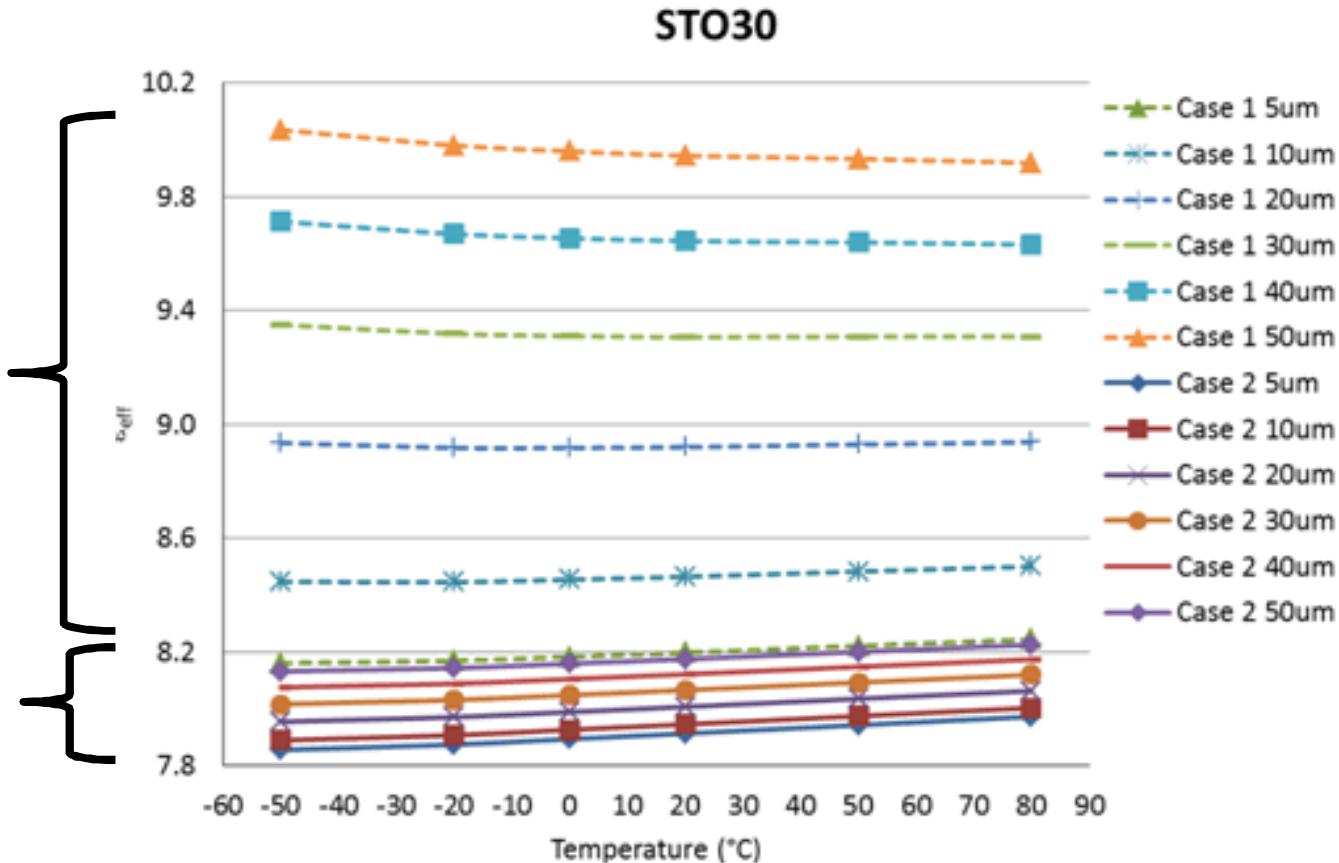
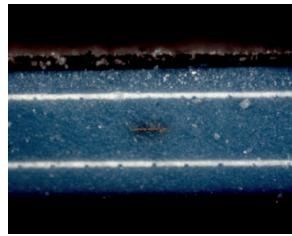
- f_r
 - STO20 shows $0\tau_f$ at 50 μm
 - STO30 shows $0\tau_f$ at 20 μm
- τ_f compensation
 - Scales to wt% of STO
 - Scales to thickness

Effect of Configuration: ϵ_{eff}

Case 1



Case 2



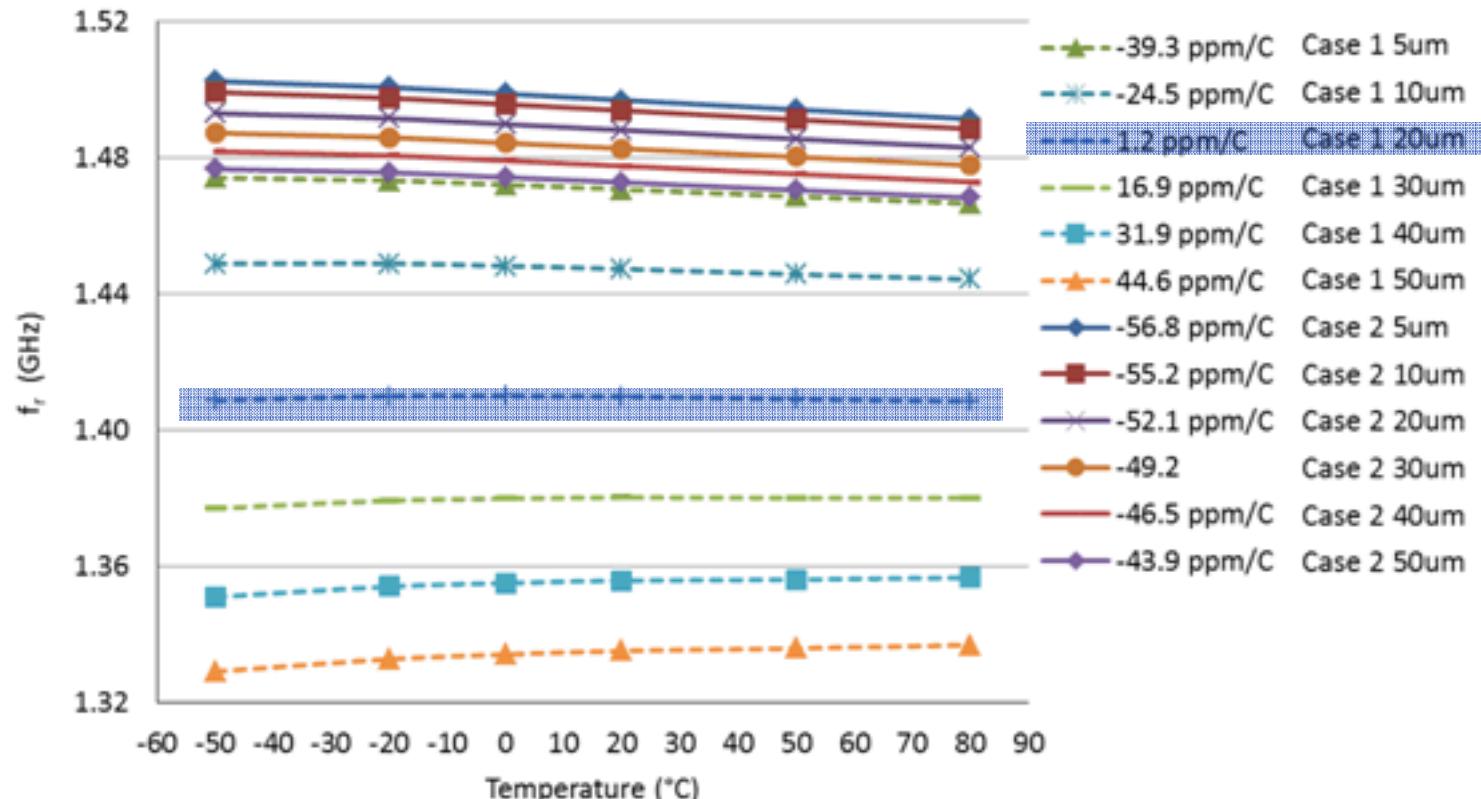
- Case 1

- Increases of ϵ_{eff} significant
- A crossover in slope

- Case 2

- Change of ϵ_{eff} minimal
- SL sees much less STO

Effect of Configuration: f_r



- f_r
 - STO30 shows $0\tau_f$ at 20 μm in case 1
 - Never reaches $0\tau_f$ in case 2
- τ_f compensation
 - Placement of STO is critical
 - Most effective when next to SL